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Document JP 2002-236080 A2**ID:****Title:** METHOD OF PREPARING OBSERVATION SAMPLE FOR TRANSMISSION ELECTRON MICROSCOPE**Assignee:** NIPPON TELEGR & TELEPH CORP**Inventor:** NAKAMURA SHINJI
UEKI TAKEMI
NAKAJIMA BAN**US Class:****Int'l Class:** G01N 1/28 A; H01J 37/20 B**Issue Date:** 08/23/2002**Filing Date:** 03/27/1995**Abstract:**

PROBLEM TO BE SOLVED: To shorten the machining time of a recessed part and to reduce the size of chips in the end parts of a protruded part.

SOLUTION: Diamond particles are fixed and held by a fixing agent made of a non-metallic material, and a diamond blade with a thickness larger than that of the recessed part 20 is used. The diamond blade is held at a holder. The outer circumferential part of the diamond blade is protruded from the holder by no more than twice the thickness of a semiconductor chip 13, and notching is performed by an amount of notching smaller than the thickness of the semiconductor chip 13. Parts adjacent to a section to be observed and analyzed on the semiconductor chip 13 are ground and machined with one feeding operation of the diamond blade to form the protruded part 19 and the recessed part 20. The diamond blade is used to perform notching by the amount of notching, corresponding to the thickness of the semiconductor chip 13 for cutting the semiconductor chip 13 and cut-out regions made of the protruded part 19 and the recessed part 20.

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